100% Material Declaration Data Sheet FTG256

Average Weight: 1.0494 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.0596**	**5.68%**
	Silicon	7440-21-3	100.00		0.0596	
Die Attach Material					**0.0062**	**0.59%**
	Silver	7440-22-4	78.00		0.0048	
	Resin	Trade Secret	22.00		0.0014	
Mold Compound					**0.5044**	**48.07%**
	Epoxy Resins	Trade Secret	12.00		0.0605	
	SiO2	60676-86-0	88.00	Filler	0.4439	
Laminate					**0.2008**	**19.14%**
	Laminate	Trade Secret	63.35		0.1272	
	Solder Mask	Trade Secret	14.39		0.0289	
	Copper	7440-50-8	16.62	Metal Layer	0.0334	
	Nickel	7440-02-0	4.80	Metal Layer	0.0097	
	Gold	7440-57-5	0.84	Metal Layer	0.0017	
Bond Wire					**0.0075**	**0.71%**
	Gold	7440-57-5	99.00		0.007436479	
	Silver	7440-22-4	0.0025		0.000000188	
	Copper	7440-50-8	0.0005		0.00000038	
	Iron	7439-89-6	0.0005		0.00000038	
	Calcium	7440-70-2	0.0020		0.000000150	
	Palladium	7440-05-3	0.9900		0.000074365	
	Magnesium	7439-95-4	0.0005		0.00000038	
Solder Balls					**0.2709**	**25.81%**
	Tin	7440-31-5	95.50		0.2587	
	Silver	7440-22-4	4.00		0.0108	
	Copper	7440-50-8	0.50		0.0014	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
6/19/06	1.1	100% Material Declaration.
9/21/06	1.2	Updated component descriptions.

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